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10/560,634	12/13/2005	Cornelis Adrianus Henricus Antonius Mutsaers	NL 030673	6812	
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P.O. BOX 300			RALEIGH, DONALD L		
BRIARCLIFF	MANOR, NY 10510		ART UNIT	PAPER NUMBER	
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Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

		$\mathcal{T}H$
	Application No.	Applicant(s)
Office Action Summary	10/560,634	MUTSAERS, CORNELIS ADRIANUS HENRICUS AN
onice Action Cummary	Examiner	Art Unit
	Donald L. Raleigh	4176
The MAILING DATE of this communication appeariod for Reply	ppears on the cover sheet v	vith the correspondence address
A SHORTENED STATUTORY PERIOD FOR REPLY WHICHEVER IS LONGER, FROM THE MAILING IDENTIFY of the may be available under the provisions of 37 CFR 1 after SIX (6) MONTHS from the mailing date of this communication. If NO period for reply is specified above, the maximum statutory period. Failure to reply within the set or extended period for reply will, by statu Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	DATE OF THIS COMMUN. .136(a). In no event, however, may a d will apply and will expire SIX (6) MO te, cause the application to become A	ICATION. Treply be timely filed NTHS from the mailing date of this communication. ABANDONED (35 U.S.C. § 133).
Status		•
1) Responsive to communication(s) filed on 24	September 2007.	·
,	is action is non-final.	,
3) Since this application is in condition for allow closed in accordance with the practice under	•	•
Disposition of Claims		
4) ⊠ Claim(s) 1-17 is/are pending in the applicatio 4a) Of the above claim(s) is/are withdres 5) □ Claim(s) is/are allowed. 6) ⊠ Claim(s) 1-17 is/are rejected. 7) □ Claim(s) is/are objected to. 8) □ Claim(s) are subject to restriction and/	awn from consideration.	
Application Papers		
9) The specification is objected to by the Examir		
10) The drawing(s) filed on is/are: a) ac		
Applicant may not request that any objection to the Replacement drawing sheet(s) including the corre	•	, ,
11) The oath or declaration is objected to by the E	·	
Priority under 35 U.S.C. § 119		
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of: 1. Certified copies of the priority document 2. Certified copies of the priority document 3. Copies of the certified copies of the priority application from the International Bureat * See the attached detailed Office action for a list	nts have been received. Its have been received in ority documents have bee au (PCT Rule 17.2(a)).	Application No n received in this National Stage
Attachment(s) 1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO/SB/08) Paper No(s)/Mail Date 12/13/05.	Paper No	Summary (PTO-413) (s)/Mail Date Informal Patent Application

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DETAILED ACTION

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claims 1-17 are rejected under 35 U.S.C. 102(b) as being anticipated by Ghosh (US PGPub. 2001/0052752 A1).

Reference Claim 1:

Ghosh teaches:

material).

A barrier laminate (Fig. 5) comprising barrier(21) and planarisation materials (Page 3 [0032] lines 3-4 teaches that this layer is a polymer.

Page 4 [0037], lines 4-5 teaches that parylene is a preferred polymer and lines 6-8 teaches that Parylene helps cover defects and pinholes, i.e. constitutes a planarisation

characterized in that said barrier laminate (21 and parylene) contains at least one discontinuous layer of a planarisation material, which layer is divided into unconnected

areas distributed along the plane.

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(In Fig.5, the first barrier layer (21)(which contains parylene) is patterned to leave open

portions of the substrate (unconnected), Page 3, [0032], lines 3-5)

Reference Claim 2:

Ghosh teaches:

Wherein said unconnected areas are separated by regions of

a barrier material. (Fig.5 shows the unconnected areas of barrier material (21) exposing

the substrate beneath. Therefore, the unconnected areas (exposed substrate) are

separated by squares of barrier material.)

Reference Claim 3:

Ghosh teaches:

Wherein said planarisation material is an organic material.

(Page 3 [0032] lines 3-4 teach that the 1st encapsulation layer may is formed of a

polymer. Page 4, [0037] teaches that parylene is a preferred polymer.

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Page 4, [0037] lines 6-8 teaches that Parylene helps cover defects and pinholes, i.e. constitutes a planarisation material. Page 4 [0037]; chemical diagrams show that Parylene is organic (contains Carbon-Hydrogen bond (CH₂))

Reference Claim 4:

Ghosh teaches:

Wherein said planarisation material is a combination of organic and inorganic materials.

(Page 4, [0037], chemical diagrams show that Parylene C & D contains Carbon-

Hydrogen bonds (CH₂) ,which is organic and Chlorine (Cl) which is inorganic.)

Reference Claim 5:

Ghosh teaches:

Wherein said barrier material is an inorganic material.

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(Both of the layers (21) and (22) can be considered as barrier layers. The second encapsulation layer (22), Page 3 [0032], lines 15-16 is formed of an oxide layer. Page 4, [0036], lines 5-9 teaches that a suitable material would be SiO₂, which is inorganic.)

Reference Claim 6:

Ghosh teaches:

Wherein said regions of a barrier material (21) forms a checked pattern.

(Fig.5 shows a checked pattern of barrer layer (21) exposing parts of the substrate (2))

Reference Claim 7:

Ghosh teaches:

Further comprising at least one continuous layer of a barrier material.

(Page 3 [0032], lines 17-19 teaches that barrier layer (22) covers layer (21) and the substrate)

Reference Claim 8:

Ghosh teaches:

Wherein said discontinuous layer is arranged between two continuous layers of a barrier material.

(Page 3, [0028], lines 8-11 teaches that the top layer of the OLED stack is a barrrier layer of ITO. Although, inventor does not specify that this layer is continuous across the

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substrate; the substrate layer beneath the OLED stack is obviously continuous and presents a barrier layer sandwiching the 1st encapsulation layer (21) and the 2nd

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encapsulation layer(22)).

Reference Claim 9:

Ghosh teaches:

Further comprising at least one continuous layer of a planarisation material.

(Page.3, [0032], lines 23-32 teaches an optional arrangement of Fig.5 with a 3rd

encapsulation layer (23) formed of a polymer that provides chemical protection. Page 4,

[0037] teaches that parylene is a polymer that provides such protection. Additionally,

Page 3 [0032], lines 31-32 teaches that an additional SiO 2 layer can be added on layer

(23) and Page 4, [0037] teaches that these oxide layers need to be protected with

parylene, which is a planarisation material.

Reference Claim 10:

Ghosh teaches:

Wherein said planarisation material is a polymeric material.

(Page 4 [0037] teaches that Parylene is a suitable polymer for the planarisation layer. (It

covers defects and pinholes, which is what a planarisation material is used for.)

Application/Control Number: 10/560,634 Art Unit: 4176 Reference Claim 11: Ghosh teaches: Wherein said planarisation material is selected from the group consisting of parylene, acrylates, epoxides, urethanes, spin-on dielectrics, and siloxanes. (Page 4 [0037], parylene) Reference Claim 12 Ghosh teaches: Wherein said barrier material is selected from the group consisting of are SiO ₂ , SiC, SisN ₄ , TiO ₂ HfO ₂ , Y ₂ O ₃ , Ta ₂ O ₃ , and Al ₂ O ₃ . (Page 4, [0036], lines 5-9, which is used for the 2 nd encapsulation (barrier) layer (22) . Page 3, [0032], lines 15-17) Reference Claim 13: Ghosh teaches:	Application/Control Number 40/500 024	Da
Ghosh teaches: Wherein said planarisation material is selected from the group consisting of parylene, acrylates, epoxides, urethanes, spin-on dielectrics, and siloxanes. (Page 4 [0037], parylene) Reference Claim 12 Ghosh teaches: Wherein said barrier material is selected from the group consisting of are SiO ₂ , SiC, SisN ₄ , TiO ₂ HfO ₂ , Y ₂ O ₃ , Ta ₂ O ₃ , and Al ₂ O ₃ . (Page 4, [0036], lines 5-9, which is used for the 2 nd encapsulation (barrier) layer (22). Page 3, [0032], lines 15-17)	·	Page 7
Wherein said planarisation material is selected from the group consisting of parylene, acrylates, epoxides, urethanes, spin-on dielectrics, and siloxanes. (Page 4 [0037], parylene) Reference Claim 12 Ghosh teaches: Wherein said barrier material is selected from the group consisting of are SiO ₂ , SiC, SisN ₄ , TiO ₂ HfO ₂ , Y ₂ O ₃ , Ta ₂ O ₃ , and Al ₂ O ₃ . (Page 4, [0036], lines 5-9, which is used for the 2 nd encapsulation (barrier) layer (22). Page 3, [0032], lines 15-17)	Reference Claim 11:	,
is selected from the group consisting of parylene, acrylates, epoxides, urethanes, spin-on dielectrics, and siloxanes. (Page 4 [0037], parylene) Reference Claim 12 Ghosh teaches: Wherein said barrier material is selected from the group consisting of are SiO ₂ , SiC, SisN ₄ , TiO ₂ HfO ₂ , Y ₂ O ₃ , Ta ₂ O ₃ , and Al ₂ O ₃ . (Page 4, [0036], lines 5-9, which is used for the 2 nd encapsulation (barrier) layer (22). Page 3, [0032], lines 15-17)	Ghosh teaches:	
epoxides, urethanes, spin-on dielectrics, and siloxanes. (Page 4 [0037], parylene) Reference Claim 12 Ghosh teaches: Wherein said barrier material is selected from the group consisting of are SiO ₂ , SiC, SisN ₄ , TiO ₂ HfO ₂ , Y ₂ O ₃ , Ta ₂ O ₃ , and Al ₂ O ₃ . (Page 4, [0036], lines 5-9, which is used for the 2 nd encapsulation (barrier) layer (22). Page 3, [0032], lines 15-17)	Wherein said planarisation material	
(Page 4 [0037], parylene) Reference Claim 12 Ghosh teaches: Wherein said barrier material is selected from the group consisting of are SiO ₂ , SiC, SisN ₄ , TiO ₂ HfO ₂ , Y ₂ O ₃ , Ta ₂ O ₃ , and Al ₂ O ₃ . (Page 4, [0036], lines 5-9, which is used for the 2 nd encapsulation (barrier) layer (22). Page 3, [0032], lines 15-17)	is selected from the group consisting of parylene, acrylates,	
Reference Claim 12 Ghosh teaches: Wherein said barrier material is selected from the group consisting of are SiO_2 , SiC , $SisN_4$, TiO_2 HfO_2 , Y_2O_3 , Ta_2O_3 , and Al_2O_3 . (Page 4, [0036], lines 5-9, which is used for the 2^{nd} encapsulation (barrier) layer (22) . Page 3, [0032], lines 15-17)	epoxides, urethanes, spin-on dielectrics, and siloxanes.	
Ghosh teaches: Wherein said barrier material is selected from the group consisting of are SiO ₂ , SiC, SisN ₄ , TiO ₂ HfO ₂ , Y ₂ O ₃ , Ta ₂ O ₃ , and Al ₂ O ₃ . (Page 4, [0036], lines 5-9, which is used for the 2 nd encapsulation (barrier) layer (22). Page 3, [0032], lines 15-17)	(Page 4 [0037], parylene)	
Ghosh teaches: Wherein said barrier material is selected from the group consisting of are SiO ₂ , SiC, SisN ₄ , TiO ₂ HfO ₂ , Y ₂ O ₃ , Ta ₂ O ₃ , and Al ₂ O ₃ . (Page 4, [0036], lines 5-9, which is used for the 2 nd encapsulation (barrier) layer (22) . Page 3, [0032], lines 15-17)		
Ghosh teaches: Wherein said barrier material is selected from the group consisting of are SiO ₂ , SiC, SisN ₄ , TiO ₂ HfO ₂ , Y ₂ O ₃ , Ta ₂ O ₃ , and Al ₂ O ₃ . (Page 4, [0036], lines 5-9, which is used for the 2 nd encapsulation (barrier) layer (22) . Page 3, [0032], lines 15-17)	Peference Claim 12	
Wherein said barrier material is selected from the group consisting of are SiO_2 , SiC , $SisN_4$, TiO_2 HfO ₂ , Y_2O_3 , Ta_2O_3 , and Al_2O_3 . (Page 4, [0036], lines 5-9, which is used for the 2^{nd} encapsulation (barrier) layer (22) . Page 3, [0032], lines 15-17)	Reference Claim 12	
SisN ₄ , TiO ₂ HfO ₂ , Y ₂ O ₃ , Ta ₂ O ₃ , and Al ₂ O ₃ . (Page 4, [0036], lines 5-9, which is used for the 2 nd encapsulation (barrier) layer (22) . Page 3, [0032], lines 15-17) Reference Claim 13:	Ghosh teaches:	
(Page 4, [0036], lines 5-9, which is used for the 2 nd encapsulation (barrier) layer (22). Page 3, [0032], lines 15-17) Reference Claim 13:	Wherein said barrier material is selected from the group consisting of a	are SiO ₂ , SiC,
Page 3, [0032], lines 15-17) Reference Claim 13:	SisN ₄ , TiO ₂ HfO ₂ , Y ₂ O ₃ , Ta ₂ O ₃ , and Al ₂ O ₃ .	
Reference Claim 13:	(Page 4, [0036], lines 5-9, which is used for the 2 nd encapsulation (barr	rier) layer (22) .
	Page 3, [0032], lines 15-17)	
		,
Ghosh teaches:	Reference Claim 13:	
	Ghosh teaches:	

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Use of a barrier laminate as an oxygen and/or water impermeable film.

(Page 4, [0038], lines 1-3 teaches that Parylene C is low in oxygen permeability and moisture vapor transmission.)

Reference Claim 14:

Ghosh teaches:

A method for the manufacture of a discontinuous layer (21) in a barrier laminate (21 and parylene) comprising:

- depositing a continuous layer of a planarisation material,
- encapsulation layer (23) formed of a polymer that provides chemical protection.

 Page 4, [0037] teaches that parylene is a polymer that provides such protection.

 Additionally, Page 3 [0032], lines 31-32 teaches that an additional SiO 2 layer can be added on layer (23) and Page 4, [0037] teaches that these oxide layers need

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to be protected with parylene , which is a planarisation material.

removing regions of said layer of a planarisation material

- (Fig.5, shows portions of layer (21) removed to expose the substrate. Page 3,

[0032], lines 3-6) and

filling said regions with a barrier material.

- (Page 3 [0032], lines 17-19 teaches the 2nd encapsulation (barrier) layer (22)

completely covering the first barrier layer (21) and the exposed substrate., i.e.

filling in the exposed regions with barrier material)

Reference Claim 15:

Ghosh teaches:

A method for the manufacture of a discontinuous layer (Fig.5 (21))

in a barrier laminate (21 and parylene) comprising:

depositing a patterned layer of a planarisation material (parylene),

whereby regions where no planarisation material is deposited are

formed, (Fig.5 shows exposed regions of the substrate that layer (21) containing the

parylene does not cover) and

- filling said regions with a barrier material.

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- (Page 3 [0032], lines 17-19 teaches the 2nd encapsulation (barrier) layer (22)

completely covering the first barrier layer (21) and the exposed substrate., i.e.

filling in the exposed regions with barrier material)

Reference Claim 16:

Ghosh teaches:

Wherein said filling of said regions with a barrier material is performed simultaneously as the deposition of a continuous layer of a barrier material on said discontinuous layer. (The deposition of the 2nd barrier layer (22) would fill in the exposed regions and simultaneously create a continuous barrier layer across the entire substrate and OEL portions)

Reference Claim 17:

Ghosh teaches:

An electronic device, or more particular electroluminescent device (Pg.1, [0005] describes the light emitting luminescent layer device (OLED), having active layers and a barrier laminate (21 and parylene)) positioned over the active layers (page 1 [0005], describes the active OLED layer and [0012] teaches encapsulating the OLED with a barrier layer (21),

the laminate (21 and parylene) having a discontinuous layer (Fig.5, shows discontinuous layer (21))

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which is, among the layers of the laminate containing planarisation material

(Page 3 [0032] lines 3-4 teaches that layer (21) is a polymer. Page 4 [0037], lines 4-5 teaches that parylene is a preferred polymer and lines 6-8 teaches that parylene helps cover defects and pinholes, i.e. constitutes a planarisation material).

the one closest to the active layers of said electroluminescent device.

(Page 1 [0012], lines 1-5 teaches placing layer (21) over the organic light emitting diode (active layer))

Conclusion

Examiner's note: Examiner has cited particular columns and line numbers in the references as applied to the claims above for the convenience of the applicant. Although the specified citations are representative of the teachings of the art and are applied to the specific limitations within the individual claim, other passages and figures may apply as well. It is respectfully requested from the applicant in preparing responses, to fully consider the references in entirety as potentially teaching all or part of the claimed invention, as well as the context of the passage as taught by the prior art or disclosed by the examiner.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Donald L. Raleigh whose telephone number is 571-270-3407. The examiner can normally be reached on Monday-Friday 7:30AM to 5:00PM EST.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Kimberly Nguyen can be reached on 571-272-2402. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

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Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

DLR

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PRIMARY EXAMINER